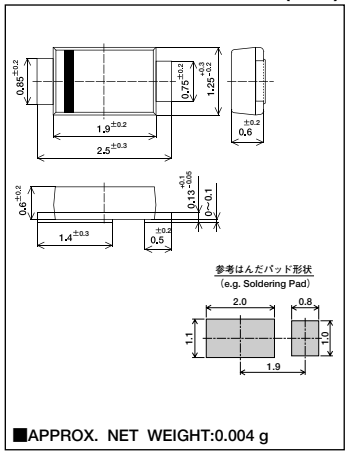
1.0A Avg. 30 Volts SBD SA10QA03

■最大定格 Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	30			V
直流順電流 Direct Forward Current	I_{DC}	直流通電 Direct Current	T_a=86℃*1	1.41	A
平均整流電流 Average rectified Forward Current	I_o	方形波通電 RECT 180℃ Rectangular Wave 50% Duty	Ta=73℃*1,V_{RM}=15V	1.0	A
			Tl=124℃,V_{RM}=15V (Tl: Lead Temperature)		
サージ順電流 Surge Forward Current	I_{FSM}	20 (50Hz正弦半波1サイクル非くり返し) Half Sine Wave,1cycle, Non-repetitive			A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	−40～+150			℃
保存温度範囲 Storage Temperature Range	T_{stg}	−40～+150			℃

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.004 g

■電気的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	V_{RM}=5V T_a=25℃		−	1	−	μA
		V_{RM}=30V T_a=25℃		−	10	100	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	I_{FM}=0.7A T_a=25℃		−	0.42	0.45	V
		I_{FM}=1.0A T_a=25℃		−	0.47	−	
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部·周囲間 (Junction to Ambient)	*1（アルミナ基板実装）	−	−	100	℃/W
			*2（ガラエポ基板実装）	−	−	150	
	$R_{th(j-l)}$	接合部·リード間（Junction to Lead）		−	−	30	

*1：プリント基板実装/Alumina Substrate Mounted (Soldering Land=6×6mm)
*2：プリント基板実装/Glass-Epoxy Substrate Mounted (Soldering Land=6×6mm)

■定格・特性曲線

FIG.1

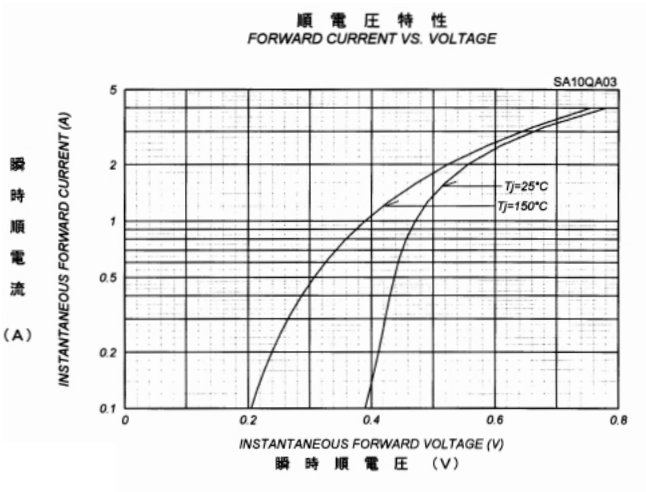


FIG.2

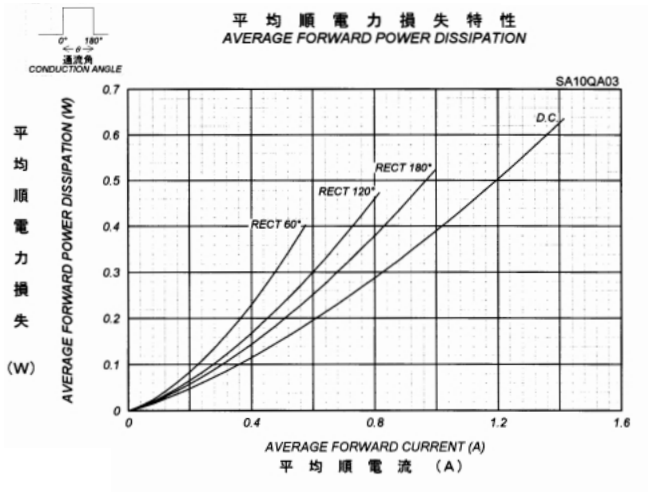


FIG.3

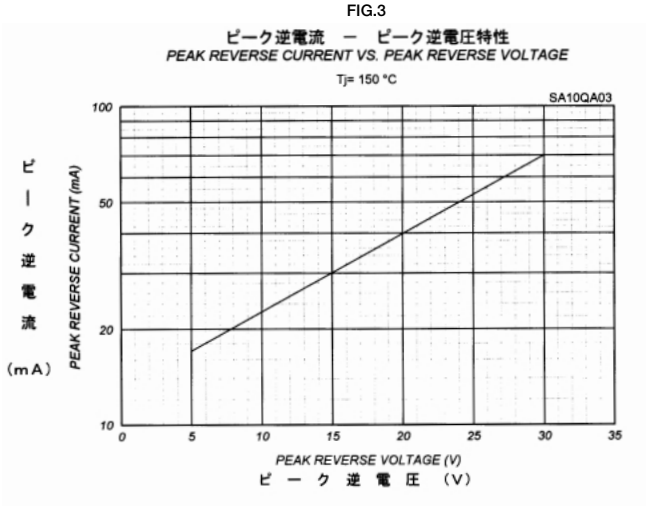


FIG.4

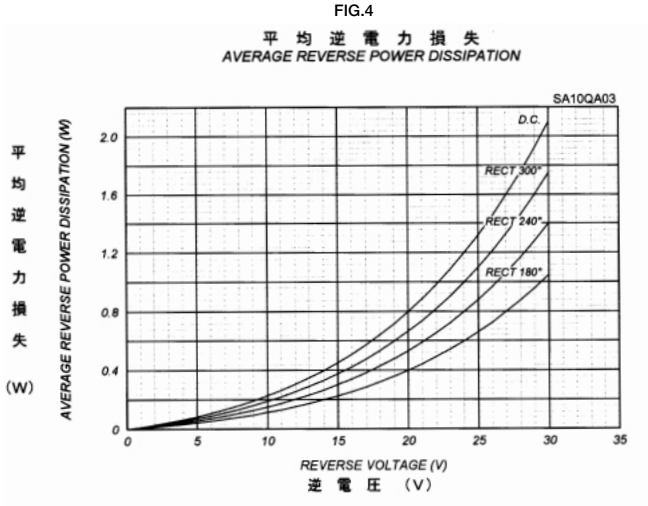


FIG.5

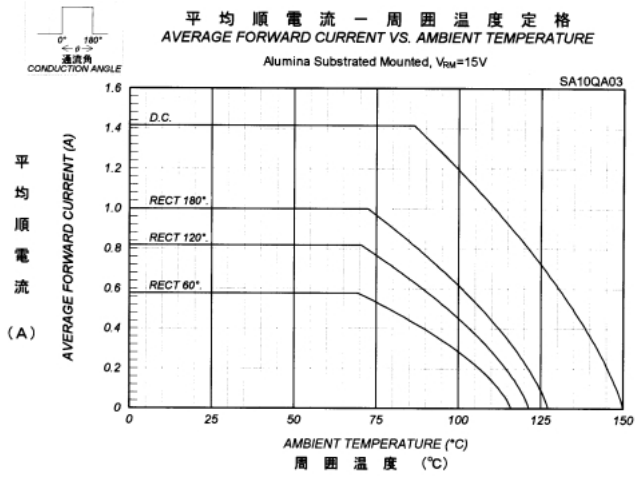


FIG.6

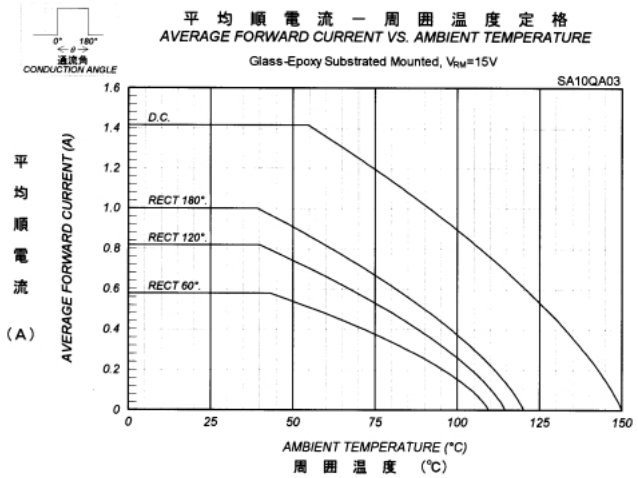


FIG.7

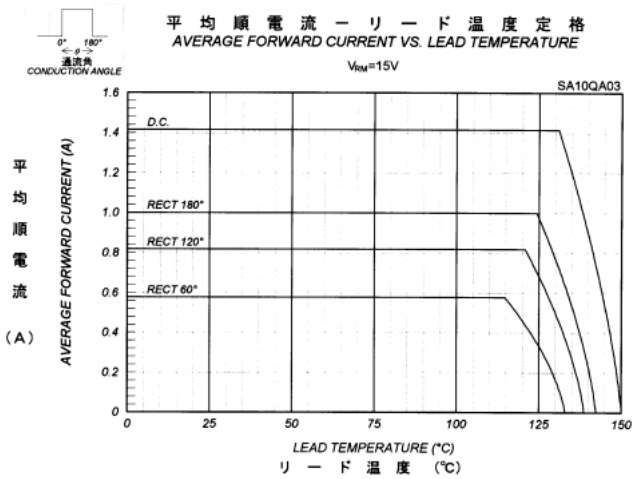


FIG.8

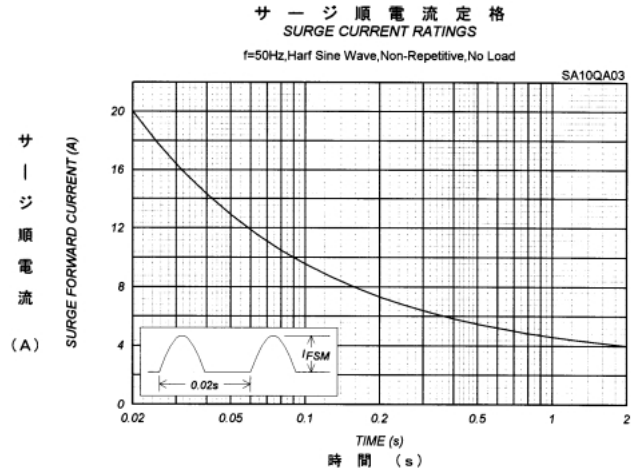


FIG.9

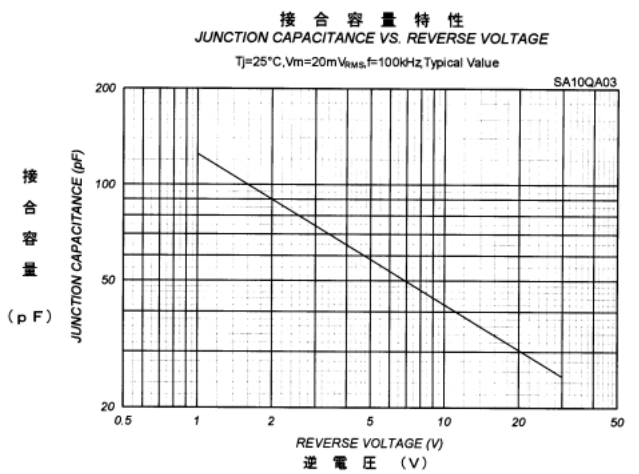


FIG.10